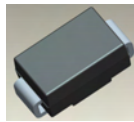


1.0A HIGH VOLTAGE SCHOTTKY BARRIER RECTIFIER
Features

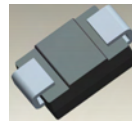
- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automated Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- High Temperature Soldering: 260°C/10 Second at Terminal
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**

Mechanical Data

- Case: SMA / SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: SMA 0.064 grams (approximate)
SMB 0.093 grams (approximate)



Top View



Bottom View

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	B170/B	B180/B	B190/B	B1100/B	Unit
Peak Repetitive Reverse Voltage	V_{RRM}					
Working Peak Reverse Voltage	V_{RWM}	70	80	90	100	V
DC Blocking Voltage	V_R					
RMS Reverse Voltage	$V_{R(RMS)}$	49	56	63	70	V
Average Rectified Output Current @ $T_T = 125^\circ\text{C}$	I_O		1.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms	I_{FSM}		30			A
Single Half Sine-Wave Superimposed on Rated Load						
Repetitive Peak Reverse Current	I_{RRM}		1.0			A

Thermal Characteristics

Characteristic	Symbol	B170/B	B180/B	B190/B	B1100/B	Unit
Typical Thermal Resistance Junction to Terminal (Note 3)	$R_{\theta JT}$		25			$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}		-65 to +150			$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V_F	-	-	0.79 0.69	V	$I_F = 1.0\text{A}, T_A = 25^\circ\text{C}$ $I_F = 1.0\text{A}, T_A = 100^\circ\text{C}$
Leakage Current (Note 4)	I_R	-	-	0.5 5.0	mA	@ Rated $V_R, T_A = 25^\circ\text{C}$ @ Rated $V_R, T_A = 100^\circ\text{C}$
Total Capacitance	C_T	-	-	80	pF	$V_R = 4\text{V}, f = 1\text{MHz}$

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/quality/lead_free.html.
 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
 3. Valid provided that terminals are kept at ambient temperature.
 4. Short duration pulse test used to minimize self-heating effect.

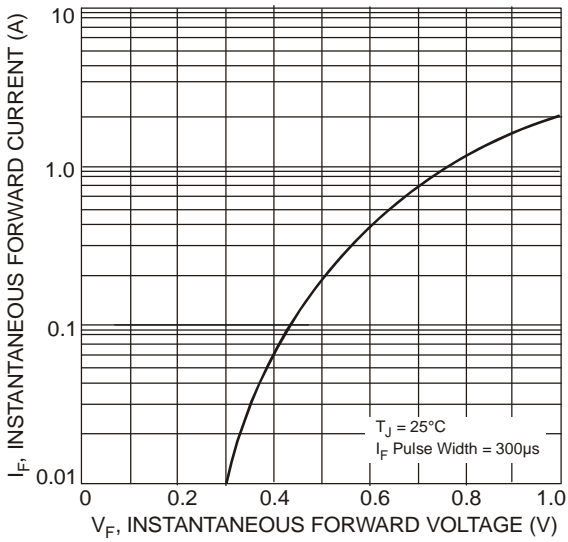


Fig. 1 Typical Forward Characteristics

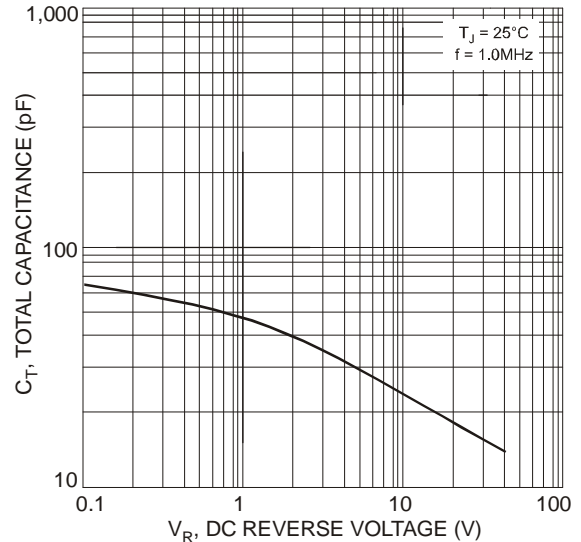


Fig. 2 Total Capacitance vs. Reverse Voltage

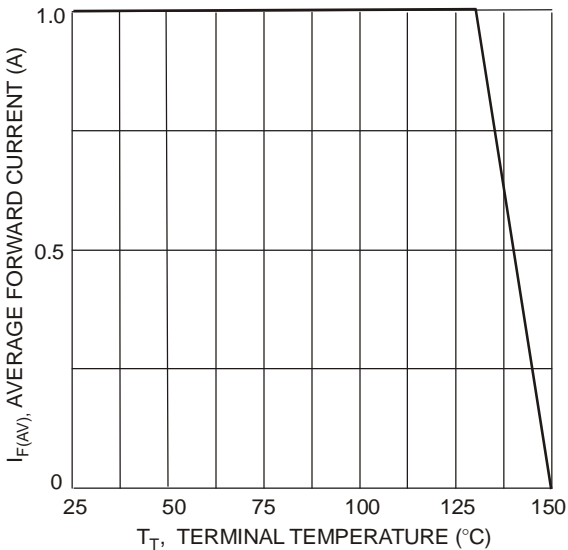


Fig. 3 Forward Current Derating Curve

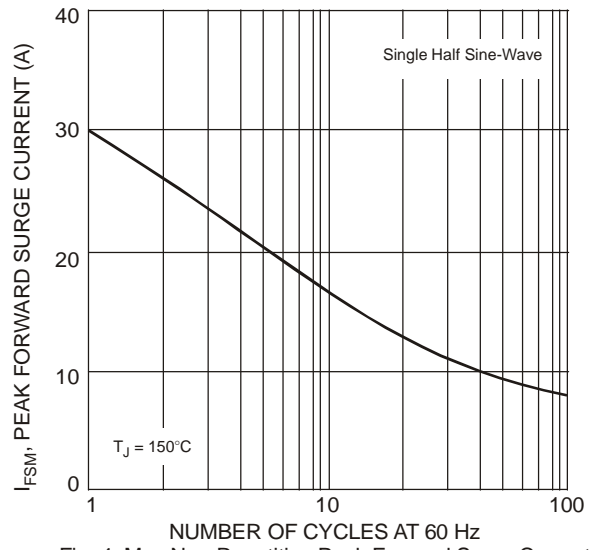


Fig. 4 Max Non-Repetitive Peak Forward Surge Current

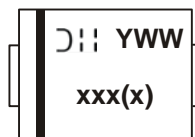
Ordering Information (Note 5)

Part Number	Case	Packaging
B1x-13-F	SMA	5000/Tape & Reel
B1xB-13-F	SMB	3000/Tape & Reel

*x = Device type, e.g. B180-13-F (SMA package); B1100B-13-F (SMB package).

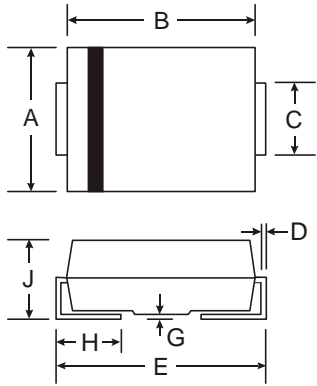
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



XXX = Product type marking code, ex: B170 (SMA package)
 XXXX = Product type marking code, ex: B190B (SMB package)
 ☺ = Manufacturers' code marking
 YWW = Date code marking
 Y = Last digit of year (ex: 2 for 2002)
 WW = Week code 01 to 52

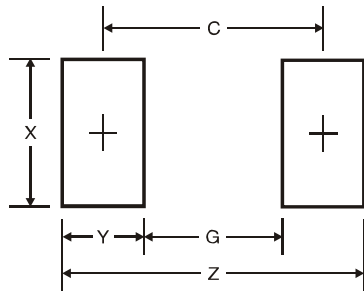
Package Outline Dimensions



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	2.01	2.30
All Dimensions in mm		

SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

Suggested Pad Layout



SMA Dimensions	Value (in mm)
Z	6.5
G	1.5
X	1.7
Y	2.5
C	4.0

SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
X	2.3
Y	2.5
C	4.3

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